# SPECIFICATIONSPEC. No. TFA7NAA00125<br/>DATE: Jul.7th,2016

То

XIAMEN XIANGGAO ELECTRONICS CO.,LTD

CUSTOMER'S PRODUCT NAME DEA162025LT-5046C1

TDK'S PRODUCT NAME DEA162025LT-5046C1

**RECEIPT CONFIRMATION** 

		DATE:	YEAR I	<u>MONTH DAY</u>
TDK Corporation Sales	ı	Engineering		
Electronic Compor Marketing Group	nents Sales &	Electronic Comp Systems, Acous	oonents Business C tics, Waves Busine	ompany ss Group
APPROVED	Person in charge	APPROVED	CHECKED	Person in charge
		N.Harada	M. Tsutsumi	M.Matsushima

# Specification Change History

## Customer's Product Name : DEA162025LT-5046C1

## TDK Product Name : DEA162025LT-5046C1

Ver.	Date	Person in charge	Change Item
-	Jul.7th,2016	M.Matsushima	Initial issue

LOW PASS FILTER Specification (TDK Part Number : DEA162025LT-5046C1)

## 1. Marking



# 2. Mechanical Outline

## 2-1 Package

Surface mount package
Tape on reel
IR-reflow
1.6 X 0.8 mm typ.
0.6 mm typ.

[ Top View ]





[Bottom View]

[Side View]



#### [ Dimension (mm) ]

(L)	(W)	(T)	(a)	(b)	(c)	(d)	(e)	(f)
1.60	0.80	0.60	0.21	0.22	0.40	0.30	0.225	0.65
+/-0.10	+/-0.10	+/-0.10	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05	+/-0.05

#### [ Pin Assignment ]

(1)	(2)	(3)	(4)
IN/OUT	GND	OUT/IN	GND

### 2-2.Coplanarity

0.05 mm max. difference in Z-direction as follows



Each terminal extends the full of DEA162025LT-5046C1. Hence any co-planarity deviation between terminals is due to curvature in the substrate. TDK guarantees that the edge of each terminal is within 0.05 mm of the horizontal plane.

## 3. Environment (Temperature & Humidity)

#### 3-1 Operating & Storage condition

Storage temperature range	: -40 ~ +85 °C
Operating temperature range	: -40 ~ +85°C
Humidity	: 0 ~ 90 % RH (Max. wet bulb temperature 38°C)

#### 3-2 Storage condition before soldering

Temperature	: +5 ~ +30 °C
Humidity	: 20 ~ 70 % RH
Term of storage	: Within 6 months
Baking	: Unnecessary

# <u>4. Electrical Specification</u> (Ta=+25<sup>o</sup>C)

Devenation	Frequency		Specification		Sample	Linit
Parameter	Band	[MHz]	Min	Max	Тур.	Offic
Insertion Loss (at 25°C)		1880 - 2025	-	1.35	1.0	dB
Insertion Loss (at -40 ~ +85 °C)	Pass Band (f1) B34 . 39	1880 - 2025	-	1.50	-	dB
VSWR (at -40 ~ +85 °C)	, ~~	1880 - 2025	-	1.7	1.2	-
	Wi-fi ISM(2.4G)	2400 - 2500	25	-	29	dB
	Wi-fi ISM(5G)	5150 - 5850	30	-	33	dB
Attonuction (st. 40, 105, 00)	2x(f1)	3760 - 4050	27	-	31	dB
Alternuation (at -40 ~ +85 °C)	3x(f1)	5640 - 6075	27	-	30	dB
	4x(f1)	7520 - 8100	17	-	21	dB
	5x(f1)	9400 - 10125	12	-	17	dB
Power Capacity		-	30	-	dBm	

We recommend to terminate for all port with 50ohm at all times.



# 6.Measuring Conditions



**Note 1**: The Port Extension function on the Network Analyzer is used to extend the calibration plane to the DUT terminals.

**Note 2**: Loss in the PCB traces is compensated for by measurement data taken on a PCB Thru' line.

# 7.Land Pattern



# 8. Environmental and quality proposal

This product satisfies the electrical specification after the following tests.

(When measured after two hours in normal conditions)

Temperature	All data initially taken at +25°C, then repeated at -40°C				
characteristics:	and again at +85℃.				
Heat proof:	+85 ℃+/-2 ℃ for 1000 hours				
Cold proof:	-40 ℃ +/-2 ℃ or 500 hours				
Moisture proof:	+60 ℃ +/-2 ℃, 90 ~95% R.H. for 1000 hours				
Heat shock:	-40 ~ +85 °C for 350 cycles				
	each cycle being 30 min				
	10-500Hz vibration frequency (10G Max.)				
Vibration:	with 1.52mmp-p amplitude for two hours in x,y,z				
	directions				
	4. 4				
	1.Acceleration 1000m/s2				
Mechanical shock:	$\angle$ . Direction X, Y, $\angle$ , X, Y, $\angle$ , axes				
	3.Time 6ms duration and 3 times in each direction				
	The dipped surface of the terminal shall be at least 75%				
	covered with solder after dipped in solder bath of 245				
Solderability	°C+/-3 ℃ for 3+/-0.5 sec.				
	Remark solder: Sn-3.0Ag-0.5Cu				
	Remark flux: Rosin 25%, Alcohol 75%				
	It shall be possible to hot air reflow the components twice				
Solder heat shock:	with a temperature profile shown below.				
	Dropped onto steel plate or concrete from 100cm height				
Drop shock:	three times .				
Bending test:	Solder specimen components on the test printed circuit				
	board(L:100 x w:40 x t:0.8mm) in appended				
	recommended PCB pattern Apply the load in direction of				
	the arrow until bending reaches 1mm for 5+/-1 sec.				



# 9. Recommended reflowing temperature profile

#### Pb free solder



## 10. Packing

### 10-1 Carrier tape

Carrier tape 1 , Material : paper



A	В	С	D	Е	F	G	Н	J	K
0.97	1.8	8.0	3.5	1.75	4.0	2.0	4.0	1.5	0.8
+/-0.05	+/-0.05	+/-0.2	+/-0.05	+/-0.1	+/-0.1	+/-0.05	+/-0.1	+0.1/-0	MAX

Carrier tape 2 , Material : PS



"Carrier tape 1" is currently adopted. "Carrier tape 2" will be running change after Feb.2016..

## 10-2. Reel Dimensions



## 10-3. Standard Reel Packaging quantities

4000pcs./reel

#### 11. Other

#### 11-1 Notice

The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

Aerospace/Aviation equipment Transportation equipment (cars, electric trains, ships, etc.) Medical equipment Power-generation control equipment Atomic energy-related equipment Seabed equipment Transportation control equipment Public information-processing equipment Military equipment Electric heating apparatus, burning equipment Disaster prevention/crime prevention equipment Safety equipment Other applications that are not considered general-purpose applications

When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

#### **11-2 Product Origin**

- 1. TDK-UGO Corporation, Akita, Japan
- 2. TDK Dalian Corporation, Dalian , China